



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20140221000  
Wafer Diameter Change for Select Devices in CS150 Process at GFAB  
Change Notification / Sample Request**

**Date:** 2/28/2014

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services  
Phone: +1(214) 480-6037  
Fax: +1(214) 480-6659

**20140221000**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
ADC12030CIWM/NOPB	null
ADC12038CIWM/NOPB	ADC12038CIWM NOPB
ADC12038CIWM/NOPB	ADC12038CIWM/NOPB
ADC12130CIWM/NOPB	null
ADC12138CIMS/NOPB	null
ADC12138CIWM/NOPB	ADC12138CIWM NOPB
ADC12138CIWM/NOPB	ADC12138CIWM/NOPB
ADC12H034CIMS/NOPB	ADC12H034CIMS NOPB
DP83910AV/NOPB	DP83910AV/NOPB
HPC36003V20/NOPB	HPC36003V20/NOPB
HPC46003V20/NOPB	HPC46003V20/NOPB
LM12458CIV/NOPB	LM12458CIV/NOPB
LM12H458CIV/NOPB	LM12H458CIV NOPB
LM12H458CIV/NOPB	LM12H458CIV/NOPB
LM12H458CIVF/NOPB	null
LM12L458CIV/NOPB	null
TP3070V-G/NOPB	TP3070V-G/NOPB
TP3070V-XG/NOPB	TP3070V-XG/NOPB
TP3071N-G/NOPB	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20140221000			<b>PCN Date:</b>	02/28/2014
<b>Title:</b>	Wafer Diameter Change for Select Devices in the CS150 Process at GFAB				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>*Proposed 1<sup>st</sup> Ship Date:</b>	05/28/2014	<b>Estimated Sample Availability:</b>	Date Provided at Sample request		
<b>Change Type:</b>					
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials			
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification			
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process			
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process			
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Wafer Fab Process			
	<input type="checkbox"/> Part number change				
<b>PCN Details</b>					
<b>Description of Change:</b>					
This change notification is to announce a wafer diameter change for select devices in the CS150 process at GFAB.					
<b>Current</b>		<b>New</b>			
Site/Process/Wafer Diameter		<a href="#">Site/Process/Wafer Diameter</a>			
GFAB6/CS150 Process/150mm		<a href="#">GFAB8/CS150 Process/200mm</a>			
The CS150 process technology was previously qualified at GFAB and has been running successfully since 2008.					
<b>Reason for Change:</b>					
Continuity of supply.					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					

<b>Changes to product identification resulting from this PCN:</b>		
<p><i>Note: This is <u>not</u> a fab site change. GFAB6 and GFAB8 are in the same location. The CSO is the differentiator between 6" (150mm) and 8" (200mm).</i></p>		
<b>Current</b>		
Chip Site	Chip site code (20L)	Chip country code (21L)
GFAB6	GF6	GBR
<b>New</b>		
<b>Chip Site</b>	<b>Chip site code (20L)</b>	<b>Chip country code (21L)</b>
<b>GFAB8</b>	<b>GF8</b>	<b>GBR</b>

**Sample Product Shipping Label (not actual product label)**

 <b>TEXAS INSTRUMENTS</b> MADE IN: Malaysia 2DC: 2Q:				(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS
MSL '2 / 260C/1 YEAR MSL 1 / 235C/UNLIM	SEAL DT 03/29/04			
OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b>				

**Product Affected:**

ADC12030CIWM/NOPB	COPC881-CAU/WM/E7001172	HPC36003V20/NOPB
ADC12030CIWMX/NOPB	COPC881-CFS/WM/E7001333	HPC36083DUI/V20/NOPB
ADC12038CIWM	COPC881-CLQ/WM/E7001130	HPC46003V20
ADC12038CIWM/NOPB	COPC881-CON/WM/E7001270	HPC46003V20/63
ADC12038CIWMX/NOPB	COPC882-CLN/WM/E7001131	HPC46003V20/63SN
ADC12130CIWM	COPC922-DNG/WM	HPC46003V20/NOPB
ADC12130CIWM/NOPB	COPC922-DNG/WM/EPDB1785	HPC46083TXQ/V30/SP108663
ADC12130CIWMX/NOPB	COPCH922-DOD/WM/E7000836	HPC46400EV20/NOPB
ADC12138CIMSAX/NOPB	COPCH922-DOD/WM/NOPB	HPC46400EV20/S7001136
ADC12138CIMSAX/NOPB	COPCJ842-CFA/WM/E7000908	LM12458CIV
ADC12138CIWM	COPCJ842-CGT/WM/EPDB2102	LM12458CIV/NOPB
ADC12138CIWM/NOPB	COPCJ842-CGT/WM/NOPB	LM12458CIVX
ADC12138CIWMX/NOPB	COPCJ842-CHM/WM/E7000938	LM12458CIVX/NOPB
ADC12H034CIMSAX	COPCJ842-CNQ/WM/E7000961	LM12H458CIV
ADC12H034CIMSAX/NOPB	COPCJ940-CCS/WM/E7001214	LM12H458CIV/NOPB
ADC12H034CIMSAX	COPCJ940-CCS/WM/NOPB	LM12H458CIVF
ADC12H034CIMSAX/NOPB	COPCJH942CGJ/WM/E7000857	LM12H458CIVF/NOPB
COPC822-ANC/WM/S7001238	COPEG884-AQC/WM/SP110451	LM12L458CIV
COPC822-APN/N/SP110434	COPEG884-CEK/WM/E7000968	LM12L458CIV/NOPB
COPC822-CEG/WM/E7001181	COPEG884-CHP/WM/E7001546	TP3070V-G
COPC822-CNH/WM/E7000887	COPEG884-CHP/WM/NOPB	TP3070V-G/63SN
COPC822-DQZ/WM/E7001168	COPEG888-CDP/V/E7001243	TP3070V-G/NOPB
COPC822-DQZ/WM/NOPB	DP83910AV/63	TP3070V-XG
COPC822-FHM/WM/SP110623	DP83910AV/63SN	TP3070V-XG/NOPB
COPC881-AJV/N/SP110088	DP83910AV/NOPB	TP3071N-G
COPC881-AWX/WM/E7002115	HPC36003V20	TP3071N-G/NOPB

Qualification Data (Approved: 01/30/2014)				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Device 1: ADC12138CIMS				
Wafer Fab Site:	GFAB8	Wafer Fab Process:	CS150	
Wafer Diameter:	200mm			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fails Lot#1Lot#2Lot#3		
Life Test	125°C (1000 Hrs)	80/0	-	-
Early Life Failure Rate	125°C (48 Hrs)	400/0	-	-

**Reference Qual Data: CS200/CS150 process flow in GFAB  
(Approved 12/19/2011)**

Qualification Device: ADC12138CIMS					
Wafer Fab Site:		GFAB8	Wafer Fab Process:		CS150
Wafer Diameter:		200mm			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size/Fails Lot#1 Lot#2 Lot#3		
Early Life Failure Rate		125°C (48 Hrs)	800/0	-	-
Operating Life		125°C (1000 Hrs)	80/0	-	-
**Temp Cycle		-65°C – 150°C (500 Cycles)	80/0	80/0	80/0
**Autoclave		121°C 100% 14.7PSI (96 Hrs)	79/0	80/0	79/0
**Biased HAST		130°C 85% 33.3PSI (96 Hrs)	80/0	80/0	80/0
HTSL		150°C (1000 Hrs)	79/0	-	-
GTLK		155°C (+/-400V)	3/0	-	-
** Preconditioning sequence: (Level 3/260C) as per JESD22-A113					
Qualification Device: ADC10064CIWM					
Wafer Fab Site:		GFAB8	Wafer Fab Process:		CS200
Wafer Diameter:		200mm			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size/Fails Lot#1 Lot#2 Lot#3		
Early Life Failure Rate		125°C (48 Hrs)	799/0	799/0	-
Operating Life		125°C (1000 Hrs)	80/0	80/0	-
**Temp Cycle		-65°C – 150°C (500 Cycles)	78/0	-	-
ESD CDM		750V	3/0	3/0	-
ESD HBM		2000V	3/0	3/0	-
ESD MM		250V	3/0	3/0	-
LUPS		25°C, 85°C, 150°C	12/0	-	-
** Preconditioning sequence: (Level 3/260C) as per JESD22-A113					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>